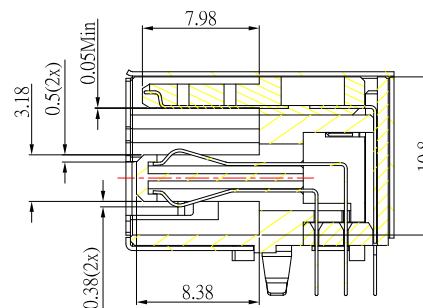
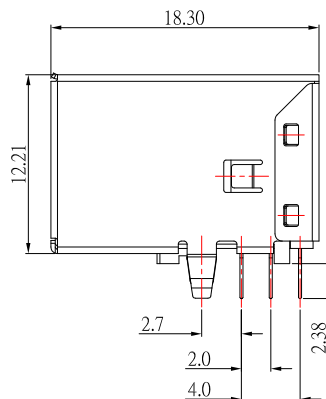
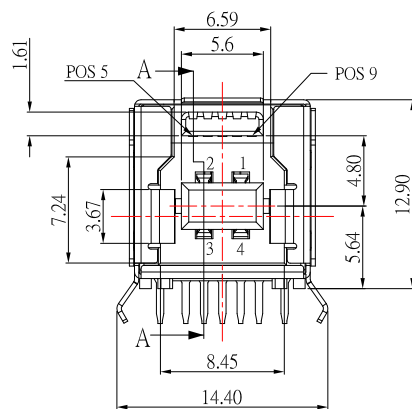




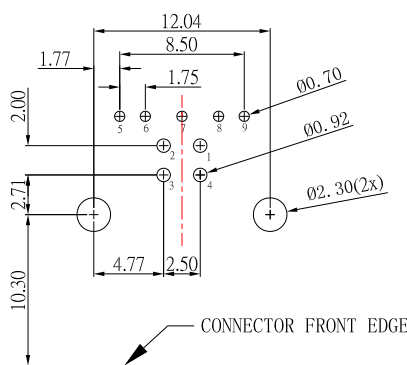
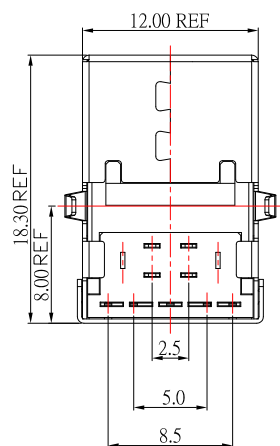
# SUB-110H-30x-S277

鍍層厚度:

Blank	: 1u"
2	: 15u"
3	: 30u"



Pin NUMBER	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	StdB_SSTX-
6	StdB_SSTX+
7	GND_DRAIN
8	StdB_SSRX-
9	StdB_SSRX+
Shell	Shield



RECOMMENDED PCB LAYOUT

**NOTE:**

**1.MATERIAL:**

- 1.1 Housing: LCP,(UL94V-0)
- 1.2 Contact: 1-4 Pin: PHOSPHOR BRONZE  
5-9 Pin: BRASS
- 1.3 Shell: BRASS

**2.Finish:**

- 2.1 Contact: Plated Gold in Mating Area ;  
Tin Plated on Solder Balls ;  
Nickel under plated overall
- 2.2 Shell: Nickel under Plated surface layer

**3.SPECIFICATION:**

- 3.1 Current Rate:1.5 A
- 3.2 insulator Resistance:1000MΩ Min
- 3.3 Dielectric Strength: 500V AC
- 3.4 Contact Resistance: 30mΩ Max
- 3.5 Operation Temperature: 0°C ~ +50°C
- 3.6 Insertion Force: 3.57 Kg Max
- 3.7 Extraction Force: 1.02 Kg Min

**CONTACT** 建倚科技股份有限公司  
**CONTACT TECHNOLOGY CORP.**

TOLERANCE UNLESS OTHERWISE STATED:  
Up to 5 ±0.2  
Above 5 ~ 15 ±0.3  
Above 15 ~ 30 ±0.4  
Above 30 ~ 50 ±0.5  
Angle ±0.3

3RD. ANGEL'S

UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	07/02/15	FINISH	MODLE	USB CONNECTOR
CHECKED BY:	DATE	SCALE	DWG NO.	SUB-110H-30x-S277
Jacky Chen	07/02/15	SHEET NO.	PART NO.	SUB-110H-30x-S277
APPROVED BY:	DATE	SIZE	VER	A1
Tony Kao	07/02/15	1 : 1	1 of 1	

1	更新SPEC及材質	Jack	070215
ITEM NO.	DESCRIPTION	DRAWN	DATE